

COST IN U.S. DOLLARS	SINCE FILE	TOTAL
	ENTRY	SESSION
FULL ESTIMATED COST	0.21	0.21

FILE 'EUROPATFULL' ENTERED AT 13:50:37 ON 15 APR 2003  
COPYRIGHT (c) 2003 WILA Verlag Muenchen (WILA)

FILE 'PATDPAFULL' ENTERED AT 13:50:37 ON 15 APR 2003  
COPYRIGHT (C) 2003 DPMA

FILE 'PCTFULL' ENTERED AT 13:50:37 ON 15 APR 2003  
COPYRIGHT (C) 2003 Univentio

FILE 'USPATFULL' ENTERED AT 13:50:37 ON 15 APR 2003  
CA INDEXING COPYRIGHT (C) 2003 AMERICAN CHEMICAL SOCIETY (ACS)

FILE 'USPAT2' ENTERED AT 13:50:37 ON 15 APR 2003  
CA INDEXING COPYRIGHT (C) 2003 AMERICAN CHEMICAL SOCIETY (ACS)

=> s Saito, Noriaki/in  
L1 48 SAITO, NORIAKI/IN

=> s novolak resin# and formaldehyde3 and (phenol or ortho-cresol or 0-cresol)  
3 FILES SEARCHED...  
L2 0 NOVOLAK RESIN# AND FORMALDEHYDE3 AND (PHENOL OR ORTHO-CRESOL OR 0-CRESOL)

=> s novolak resin# and formaldehyde and (phenol or ortho-cresol or o-cresol)  
L3 4266 NOVOLAK RESIN# AND FORMALDEHYDE AND (PHENOL OR ORTHO-CRESOL OR O-CRESOL)

=> s l3 and oxalic acid catalyst#  
L4 48 L3 AND OXALIC ACID CATALYST#

=> s l4 and temperature# and pressure  
L5 17 L4 AND TEMPERATURE# AND PRESSURE

=> s l5 and ortho ratio  
L6 1 L5 AND ORTHO RATIO

=> d

L6 ANSWER 1 OF 1 USPATFULL

	<b>Full</b>	<b>Citing</b>
	<b>Text</b>	<b>References</b>
AN	2002:172464 USPATFULL	
TI	Method of producing <b>novolak resin</b>	
IN	Saito, Noriaki, Toyonaka-shi, JAPAN Aizu, Ichishi, Niihama-shi, JAPAN Nakajima, Nobuyuki, Niihama-shi, JAPAN Fujiwara, Masahiro, Niihama-shi, JAPAN Yano, Koji, Niihama-shi, JAPAN	
PA	SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)	
PI	US 2002091224	A1 20020711
AI	US 2001-364	A1 20011204 (10)
PRAI	JP 2000-377258	20001212
	JP 2000-377259	20001212
	JP 2001-153632	20010523
DT	Utility	
FS	APPLICATION	
LN.CNT	579	
INCL	INCLM: 528/129.000	
NCL	NCLM: 528/129.000	
IC	[7]	

ICM: C08G008-04  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> d 15 1-17

L5 ANSWER 1 OF 17 EUROPATFULL COPYRIGHT 2003 WILA

Full  
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

AN 342035 EUROPATFULL ED 20000917 EW 198946 FS OS STA B  
TIEN Powdered epoxy resin compositions.  
TIDE Pulverfoermige Epoxydharzzusammensetzungen.  
TIFR Compositions de resines epoxydes sous forme de poudre.  
IN Bymark, Richard M. c/o Minnesota Mining and, Manufacturing Company 3M  
Austin Center, P.O. Box 2963 Austin Texas 78769-2963, US;  
Kirk, Alan R. c/o Minnesota Mining and, Manufacturing Company 2501  
Hudson Road P.O.Box, 33427 St. Paul, Minnesota 55133-3427, US;  
Griggs, Allen L. c/o Minnesota Mining and, Manufacturing Company 2501  
Hudson Road P.O.Box, 33427 St. Paul Minnesota 55133-3427, US;  
Martin, Steven J. c/o Minnesota Mining and, Manufacturing Company 2501  
Hudson Road P.O. Box, 33427 St. Paul, Minnesota 55133-3427, US  
PA MINNESOTA MINING AND MANUFACTURING COMPANY, P.O. Box 33427, St. Paul  
Minnesota 55133-3427, US  
SO Wila-EPZ-1989-H46-T1  
DS R DE; R FR; R GB; R IT  
PIT EPA2 EUROPAEISCHE PATENTANMELDUNG  
PI EP 342035 A2 19891115  
OD 19891115  
AI EP 1989-304781 19890511  
PRAI US 1988-193498 19880512  
IC ICM C08G059-62  
ICS C09D003-58 C09D005-00

L5 ANSWER 2 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full  
Text

AN 2002031011 PCTFULL ED 20020515 EW 200216  
TIEN FRACTIONATION OF RESINS USING A STATIC MIXER AND A LIQUID-LIQUID  
CENTRIFUGE  
TIFR FRACTIONNEMENT DE RESINES AU MOYEN D'UN MELANGEUR FIXE ET D'UNE  
CENTRIFUGEUSE LIQUIDE-LIQUIDE  
IN WANAT, Stanley, F., 3 Frances Lane, Scotch Plains, NJ 07076, US;  
RAHMAN, M., Dalil, 62 Concord Ridge Road, Flemington, NJ 08822, US;  
XIANG, Zhong, 1142 Easton Avenue, Apartment G, Somerset, NJ 08873, US  
PA CLARIANT INTERNATIONAL LTD, Rothausstrasse 61, CH-4132 Muttenez, CH [CH,  
CH], for JP only;  
CLARIANT FINANCE (BVI) LIMITED, Wickhams Cay, P.O. Box 662, Road Town,  
Tortola, VG [-, -], for all designates States except JP  
AG HUETTER, Klaus, Clariant Service GmbH, Patente, Marken, Lizenzen, Am  
Unisys-Park 1, 65843 Sulzbach, DE  
LAF English  
LA English  
DT Patent  
PI WO 2002031011 A2 20020418  
DS W: CN JP KR SG  
RW (EPO): AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE TR  
AI WO 2001-EP11357 A 20011002  
PRAI US 2000-09/687,137 20001013  
US 2000-09/698,724 20001027  
ICM C08G008-00  
ICS B01D017-038; G03F007-023

L5 ANSWER 3 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full  
Text

AN 2000033137 PCTFULL ED 20020515  
 TIEN PREPARATION OF FRACTIONATED **NOVOLAK RESINS** BY A NOVEL EXTRACTION  
 TECHNIQUE  
 TIFR NOUVELLE TECHNIQUE D'EXTRACTION POUR LA PREPARATION DE RESINES NOVOLAQUE  
 FRACTIONNEES  
 IN WANAT, Stanley, F.;  
 RAHMAN, Dalil, M.;  
 KOKOSZKA, John, J.;  
 NARASIMHAN, Balaji  
 PA CLARIANT INTERNATIONAL LTD.  
 LA English  
 DT Patent  
 PI WO 2000033137 A2 20000608  
 DS W: CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL  
 PT SE  
 AI WO 1999-EP8391 A 19991103  
 PRAI US 1998-09/190,763 19981112  
 ICM G03F007-023  
 ICS C08G008-08

L5 ANSWER 4 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full  
Text

AN 1999031157 PCTFULL ED 20020515  
 TIEN FRACTIONATED **NOVOLAK RESIN** AND PHOTORESIST COMPOSITION THEREFROM  
 TIFR RESINE NOVOLAK FRACTIONNEE ET COMPOSITION DE RESINE PHOTOSENSIBLE  
 QU'ELLE PERMET D'OBTENIR  
 IN RAHMAN, M., Dalil;  
 COOK, Michelle, M.;  
 LU, Ping-Hung  
 PA CLARIANT INTERNATIONAL, LTD.  
 LA English  
 DT Patent  
 PI WO 9931157 A1 19990624  
 DS W: CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL  
 PT SE  
 AI WO 1998-EP7754 A 19981201  
 PRAI US 1997-08/991,034 19971215  
 ICM C08G008-08  
 ICS G03F007-023

L5 ANSWER 5 OF 17 USPATFULL

Full  
Text

Citing  
References

AN 2003:92961 USPATFULL  
 TI Negative photoresist compositions for the formation of thick films,  
 photoresist films and methods of forming bumps using the same  
 IN Saito, Koji, Kanagawa, JAPAN  
 Misumi, Kouichi, Kanagawa, JAPAN  
 Okui, Toshiki, Kanagawa, JAPAN  
 Komano, Hiroshi, Kanagawa, JAPAN  
 PA TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)  
 PI US 2003064319 A1 20030403  
 AI US 2002-147984 A1 20020520 (10)  
 PRAI JP 2001-151131 20010521  
 DT Utility  
 FS APPLICATION  
 LN.CNT 903  
 INCL INCLM: 430/270.100  
 INCLS: 430/325.000

NCL NCLM: 430/270.100  
NCLS: 430/325.000  
IC [7]  
ICM: G03F007-038

L5 ANSWER 6 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 2003:86101 USPATFULL  
TI Positive photoresist composition for the formation of thick films, photoresist film and method of forming bumps using the same  
IN Misumi, Kouichi, Kanagawa, JAPAN  
Saito, Koji, Kanagawa, JAPAN  
Okui, Toshiki, Kanagawa, JAPAN  
Komano, Hiroshi, Kanagawa, JAPAN  
PA TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)  
PI US 2003059706 A1 20030327  
AI US 2002-90170 A1 20020305 (10)  
PRAI JP 2001-61565 20010306  
DT Utility  
FS APPLICATION  
LN.CNT 867  
INCL INCLM: 430/190.000  
INCLS: 430/189.000; 430/193.000  
NCL NCLM: 430/190.000  
NCLS: 430/189.000; 430/193.000  
IC [7]  
ICM: G03C001-52

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 7 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 2003:26414 USPATFULL  
TI Fractionation of resins using a static mixer and a liquid-liquid centrifuge  
IN Wanat, Stanley F., Scotch Plains, NJ, United States  
Rahman, M. Dalil, Flemington, NJ, United States  
Xiang, Zhong, Somerset, NJ, United States  
PA Clariant Finance (BVI) Limited, VIRGIN ISLANDS (BRITISH) (non-U.S. corporation)  
PI US 6512087 B1 20030128  
AI US 2000-698724 20001027 (9)  
RLI Continuation-in-part of Ser. No. US 2000-687137, filed on 13 Oct 2000  
DT Utility  
FS GRANTED  
LN.CNT 947  
INCL INCLM: 528/502.000D  
INCLS: 528/129.000; 528/148.000; 430/192.000; 430/193.000; 210/634.000  
NCL NCLM: 528/502.000D  
NCLS: 210/634.000; 430/192.000; 430/193.000; 528/129.000; 528/148.000  
IC [7]  
ICM: C08F006-04  
ICS: G03F007-023  
EXF 430/270-1; 430/192; 430/193; 430/325; 430/326; 430/330; 528/148; 528/129; 528/502D; 210/634

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 8 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 2002:172464 USPATFULL  
TI Method of producing **novolak resin**  
IN Saito, Noriaki, Toyonaka-shi, JAPAN

Aizu, Ichishi, Niihama-shi, JAPAN  
 Nakajima, Nobuyuki, Niihama-shi, JAPAN  
 Fujiwara, Masahiro, Niihama-shi, JAPAN  
 Yano, Koji, Niihama-shi, JAPAN

PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)

PI US 2002091224 A1 20020711

AI US 2001-364 A1 20011204 (10)

PRAI JP 2000-377258 20001212

JP 2000-377259 20001212

JP 2001-153632 20010523

DT Utility

FS APPLICATION

LN.CNT 579

INCL INCLM: 528/129.000

NCL NCLM: 528/129.000

IC [7]

ICM: C08G008-04

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 9 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 2000:125188 USPATFULL

TI Preparation of fractionated **novolak resins** by a novel extraction technique

IN Wanat, Stanley F., Scotch Plains, NJ, United States

Rahman, M. Dalil, Somerville, NJ, United States

Kokoszka, John J., Warwick, RI, United States

Narasimhan, Balaji, Highland Park, NJ, United States

PA Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S. corporation)

PI US 6121412 20000919

AI US 1999-418239 19991014 (9)

RLI Continuation-in-part of Ser. No. US 1998-190763, filed on 12 Nov 1998, now abandoned

DT Utility

FS Granted

LN.CNT 1037

INCL INCLM: 528/502.000D

INCLS: 528/129.000; 528/144.000; 528/491.000; 430/270.100; 438/455.000; 438/689.000; 427/352.000; 427/372.200; 210/634.000

NCL NCLM: 528/502.000D

NCLS: 210/634.000; 427/352.000; 427/372.200; 430/270.100; 438/455.000; 438/689.000; 528/129.000; 528/144.000; 528/491.000

IC [7]

ICM: C08F006-04

ICS: C08F006-22; C08G014-04

EXF 528/502D; 528/129; 528/144; 528/491; 430/270.1; 427/352; 427/372.2; 210/634; 438/455; 438/689

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 10 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 2000:40811 USPATFULL

TI Fractionated **novolak resin** and photoresist composition therefrom

IN Rahman, M. Dalil, Flemington, NJ, United States

Cook, Michelle, Somerville, NJ, United States

Lu, Ping-Hung, Bridgewater, NJ, United States

PA Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S. corporation)

PI US 6045966 20000404

AI US 1997-991034 19971215 (8)

DT Utility

FS Granted  
 LN.CNT 964  
 INCL INCLM: 430/270.100  
 INCLS: 430/311.000; 528/155.000; 528/165.000  
 NCL NCLM: 430/270.100  
 NCLS: 430/311.000; 528/155.000; 528/165.000  
 IC [7]  
 ICM: G03C005-00  
 EXF 528/155; 528/165; 430/270.1; 430/311  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 11 OF 17 USPATFULL

Full Text	Citing References
--------------	----------------------

AN 97:123007 USPATFULL  
 TI Positive photoresist coating solution comprising a mixed solvent of  
 propylene glycol monopropyl ether and 2-heptanone  
 IN Ohno, Hayato, Kanagawa, Japan  
 Nakao, Taku, Kanagawa, Japan  
 Harada, Hisanobu, Kanagawa, Japan  
 Hidesaka, Shinichi, Kanagawa, Japan  
 Kohara, Hidekatsu, Kanagawa, Japan  
 Nakayama, Toshimasa, Kanagawa, Japan  
 PA Tokyo Ohka Kogyo Co., LTD., Kanagawa, Japan (non-U.S. corporation)  
 PI US 5702862 19971230  
 AI US 1997-797663 19970131 (8)  
 PRAI JP 1996-40461 19960202  
 DT Utility  
 FS Granted

LN.CNT 481  
 INCL INCLM: 430/191.000  
 INCLS: 430/192.000; 430/193.000  
 NCL NCLM: 430/191.000  
 NCLS: 430/192.000; 430/193.000  
 IC [6]  
 ICM: G03F007-023  
 EXF 430/191; 430/192; 430/193  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 12 OF 17 USPATFULL

Full Text	Citing References
--------------	----------------------

AN 86:52384 USPATFULL  
 TI Aromatic carboxylic acid and metal-modified phenolic resins and methods  
 of preparation  
 IN Ginter, James W., Cheektowaga, NY, United States  
 Thorpe, Donald H., Williamsville, NY, United States  
 Cooke, Victor F. G., Youngstown, NY, United States  
 PA Occidental Chemical Corporation, Niagara Falls, NY, United States (U.S.  
 corporation)  
 PI US 4612254 19860916  
 AI US 1985-709461 19850307 (6)  
 DT Utility  
 FS Granted  
 LN.CNT 1586  
 INCL INCLM: 428/531.000  
 INCLS: 346/210.000; 346/211.000; 346/212.000; 346/216.000; 346/217.000;  
 346/225.000; 428/327.000; 428/326.000; 524/509.000; 524/510.000;  
 524/595.000; 524/596.000; 525/506.000; 525/508.000; 528/139.000;  
 528/140.000; 528/144.000; 528/146.000; 528/147.000; 528/148.000  
 NCL NCLM: 503/210.000  
 NCLS: 428/326.000; 428/327.000; 503/211.000; 503/212.000; 503/216.000;  
 503/217.000; 503/225.000; 524/509.000; 524/510.000; 524/595.000;  
 524/596.000; 525/506.000; 525/508.000; 528/139.000; 528/140.000;

528/144.000; 528/146.000; 528/147.000; 528/148.000

IC [4]  
 ICM: C08G008-32  
 ICS: C08L061-14  
 EXF 525/506; 525/508; 528/148; 528/139; 528/140; 528/144; 528/146; 528/147;  
 524/596; 524/509; 524/510; 524/595; 346/210; 346/211; 346/212; 346/216;  
 346/217; 346/225; 428/327; 428/326; 428/531  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 13 OF 17 USPATFULL

Full Text	Citing References
--------------	----------------------

AN 82:27450 USPATFULL  
 TI Catechol resins for the shell process  
 IN Craig, Robert S., Hoffman Estates, IL, United States  
 PA Acme Resin Corporation, Englewood Cliffs, NJ, United States (U.S.  
 corporation)  
 PI US 4333513 19820608  
 AI US 1981-240641 19810305 (6)  
 RLI Division of Ser. No. US 1979-90388, filed on 1 Nov 1979, now patented,  
 Pat. No. US 4281090, issued on 8 Jul 1981 which is a division of Ser.  
 No. US 1978-869407, filed on 16 Jan 1978, now patented, Pat. No. US  
4206262, issued on 3 Jun 1980  
 DT Utility  
 FS Granted  
 LN.CNT 296  
 INCL INCLM: 164/526.000  
 INCLS: 264/220.000; 264/221.000  
 NCL NCLM: 164/526.000  
 NCLS: 264/220.000; 264/221.000  
 IC [3]  
 ICM: B22C001-22  
 EXF 164/526; 264/220; 264/221; 525/501; 260/38  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 14 OF 17 USPATFULL

Full Text	Citing References
--------------	----------------------

AN 81:40957 USPATFULL  
 TI Catechol resins for the shell process  
 IN Craig, Robert S., Hoffman Estates, IL, United States  
 PA Acme Resin Corporation, Forest Park, IL, United States (U.S.  
 corporation)  
 PI US 4281090 19810728  
 AI US 1979-90388 19791101 (6)  
 RLI Division of Ser. No. US 1978-869407, filed on 16 Jan 1978, now patented,  
 Pat. No. US 4206262  
 DT Utility  
 FS Granted  
 LN.CNT 277  
 INCL INCLM: 525/501.000  
 INCLS: 260/038.000  
 NCL NCLM: 525/501.000  
 NCLS: 523/145.000; 524/541.000  
 IC [3]  
 ICM: C08L061-12  
 EXF 525/495; 525/501; 528/155; 260/DIG.40; 260/38  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 15 OF 17 USPATFULL

Full Text	Citing References
--------------	----------------------

AN 80:27035 USPATFULL  
 TI Catechol resins for the shell process

IN Craig, Robert S., Hoffman Estates, IL, United States  
PA Acme Resin Corporation, Forest Park, IL, United States (U.S. corporation)  
PI US 4206262 19800603  
AI US 1978-869407 19780116 (5)  
DT Utility  
FS Granted  
LN.CNT 290  
INCL INCLM: 428/404.000  
INCLS: 260/038.000; 428/407.000; 164/043.000  
NCL NCLM: 428/404.000  
NCLS: 164/021.000; 164/526.000; 428/407.000; 524/448.000  
IC [2]  
ICM: B32B019-04  
ICS: B32B027-14; B32B027-47  
EXF 428/404; 428/407; 428/403; 428/454; 428/524; 260/38; 260/DIG.40; 427/221  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 16 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 78:7183 USPATFULL  
TI Plugging compositions for blast furnace tap holes  
IN Funabiki, Kyohei, Fujieda, Japan  
Tokunaga, Tetsuya, Fujieda, Japan  
PA Sumitomo Durez Company, Ltd., Tokyo, Japan (non-U.S. corporation)  
PI US 4072531 19780207  
AI US 1976-666290 19760312 (5)  
RLI Continuation-in-part of Ser. No. US 1975-639679, filed on 11 Dec 1975, now Defensive Publication No.  
PRAI JP 1975-30669 19750315  
DT Utility  
FS Granted  
LN.CNT 280  
INCL INCLM: 106/056.000  
INCLS: 106/055.000; 106/058.000; 106/065.000; 106/067.000; 260/038.000  
NCL NCLM: 523/140.000  
NCLS: 501/099.000; 501/109.000; 501/127.000; 501/128.000; 501/130.000; 524/594.000  
IC [2]  
ICM: C04B035-02  
ICS: C04B035-66; C04B035-04; C04B035-66  
EXF 106/56; 106/67; 106/65; 106/58; 106/55; 260/38  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 17 OF 17 USPATFULL

Full Text	Citing References
-----------	-------------------

AN 76:42905 USPATFULL  
TI Process for preparing phenolic filaments  
IN Koyama, Hiroaki, Osaka, Japan  
PA Nippon Kynol Inc., Osaka, Japan (non-U.S. corporation)  
PI US 3972959 19760803  
AI US 1974-517029 19741022 (5)  
PRAI JP 1973-119673 19731024  
DT Utility  
FS Granted  
LN.CNT 741  
INCL INCLM: 260/841.000  
INCLS: 008/115.500; 260/054.000; 260/055.000; 260/056.000; 260/059.000R; 260/843.000; 260/847.000; 260/848.000; 264/176.000F; 264/236.000; 264/347.000  
NCL NCLM: 525/429.000  
NCLS: 008/115.560; 264/211.150; 264/211.160; 264/236.000; 264/347.000;



525/160.000; 525/164.000; 525/442.000; 528/493.000; 528/496.000  
IC {2}  
ICM: D06M013-12  
ICS: D06M013-16; D06M013-20  
EXF 260/59R; 260/841; 264/177F; 264/176F; 264/236; 264/347; 008/115.5  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=>